Product End-of-Life Disassembly Instructions

Marketing Name / Model [List multiple models if applicable.]	Product Category
HP ProLiant DL585 G7	Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB / PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Depending on Power Supply model number	2

External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx screw driver	T15
Flat head screw driver	Medium
Philips Driver	# 2

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

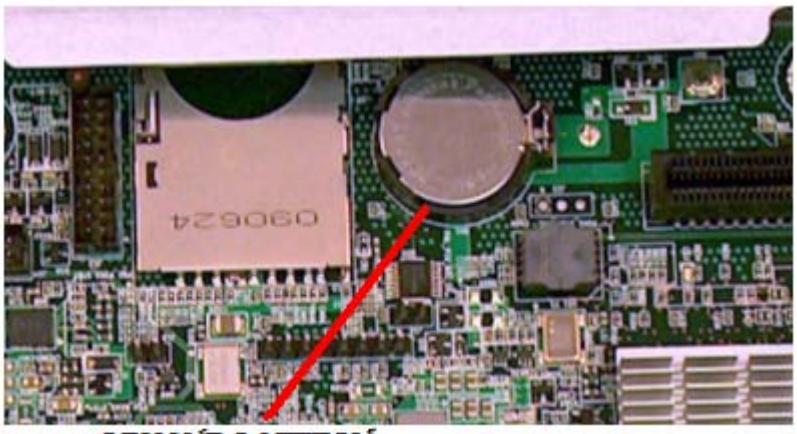
1. System Board Battery - Remove the top cover and locate the battery on the system board. Use a medium flat head screwdriver or fingers to remove the battery and dispose of properly
2. BBWC Battery – With a medium flat head screw driver remove the BBWC battery and dispose of properly.
3. Capacitors=>2.5CM - Remove the power supply from the system using a T-15 driver. With #2 Philips screw driver, remove the screws securing the top cover, then locate the capacitors and pry from the PCB with a medium flat head screw driver and dipose of properly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

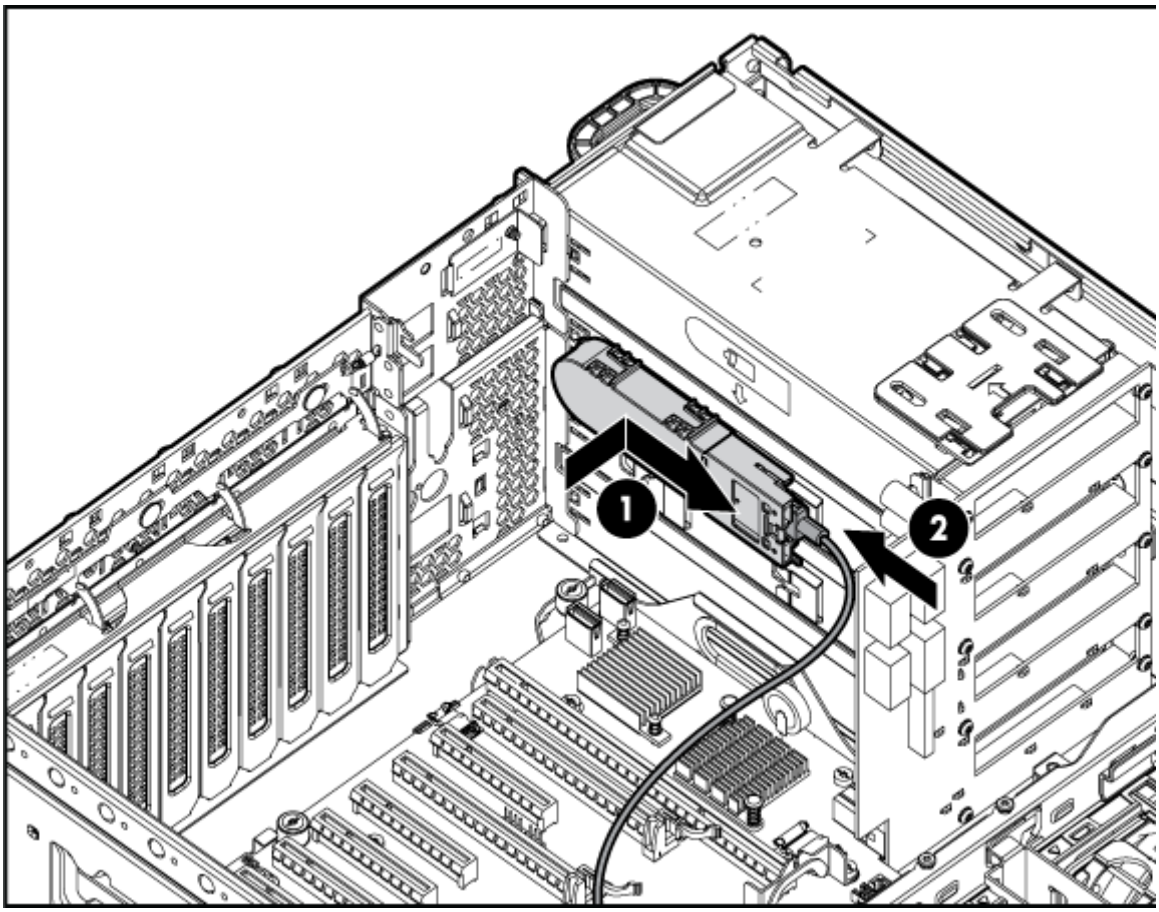
Attachment 1 – System Battery Location

Attachment 2- Location of BBWC Battery

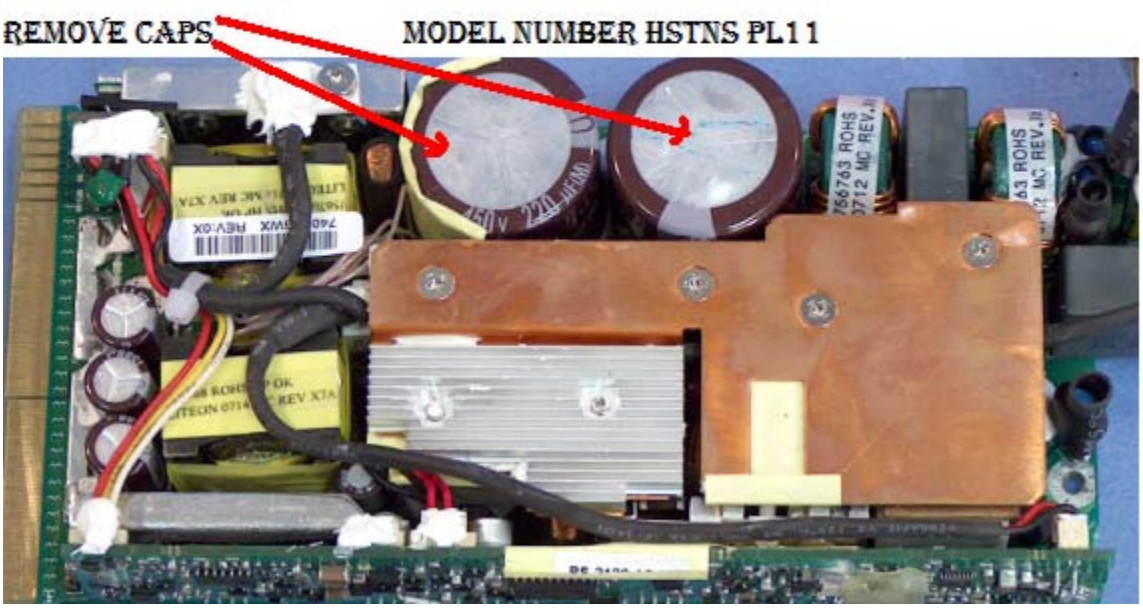
Attachment 3,4,5- Capacitor location by model number of supply



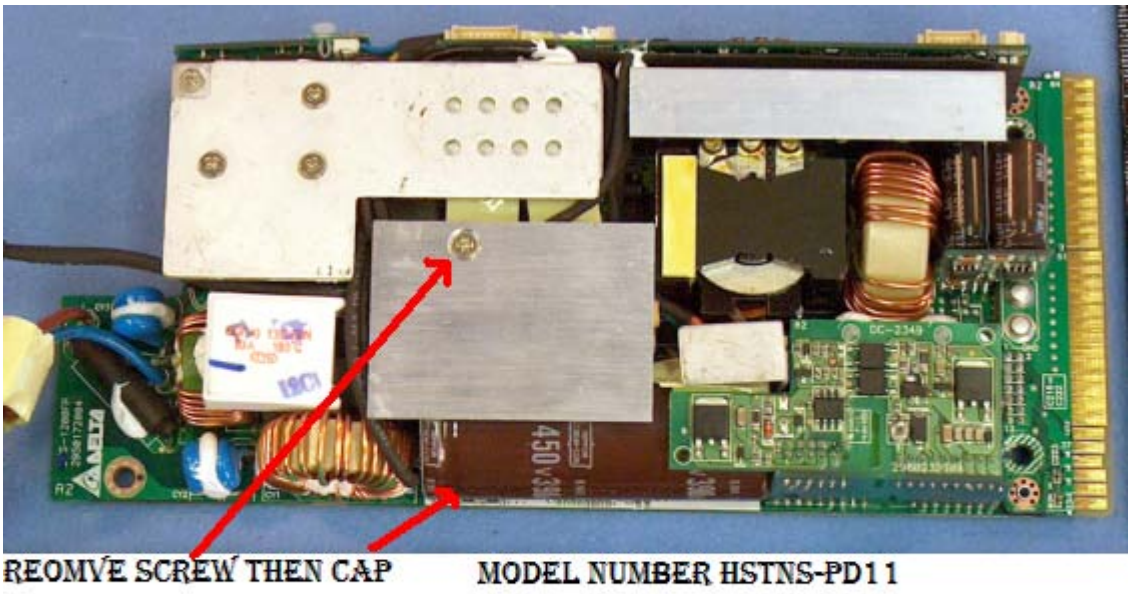
Attachment 1



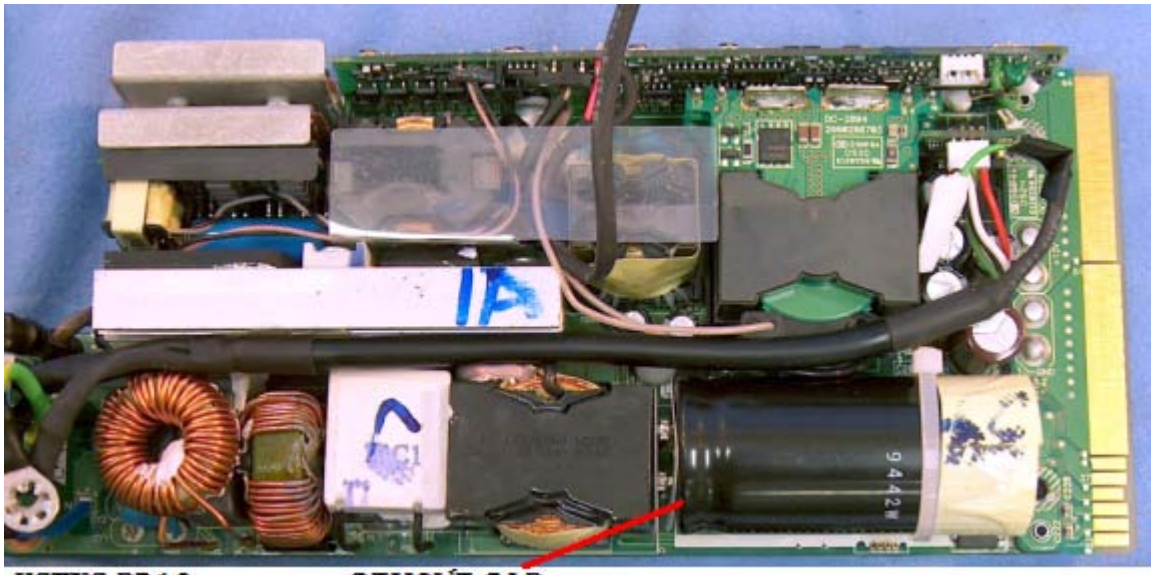
Attachment 2



Attachment 3



Attachment 4



Attachment 5